PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/23/14143
1.3 Title of PCN	SPC58NH9xC3x (FC92): BGA 17x17 Activation of ASE as Additional Assembly Plant
1.4 Product Category	see list
1.5 Issue date	2023-05-23

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.1.2 Marketing Manager	Matteo MOIOLI
2.1.3 Quality Manager	Alberto MERVIC

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcon ASE - Taiwan receiving Plant

4. Description of change

	Old	New
4.1 Description	ST Kirkop - Malta Assy Plant	ST Kirkop - Malta and ASE - Taiwan Assy Plants
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule

7.1 Date of qualification results	2023-12-31
7.2 Intended start of delivery	2023-12-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

14143 Public product.pdf
14143 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC58NH92C3RMI0X	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE

SPC58NH9xC3x (FC92): BGA 17x17 Activation of ASE as Additional Assembly Plant

IMPACTED PRODUCTS

FPBGA 17X17X1.8:

- FC92 – Chorus 10M

MANUFACT. STEP

Assembly

INVOLVED PLANT

Subcontractor ASE – Taiwan

CHANGE REASON

Service – Dual source & Capacity Improvement.

Expansion of current assembly and testing capacity (volumes increase) and flexible/secure production asset – dual sourcing strategy.

CHANGE DESCRIPTION

Activation of ASE as additional BE Assembly plant.

Here below package Bill Of Material comparison

	Malta	ASE
Substrate	HL832NS	HL832NS
Glue	2000S	2100A
Resin	GE-100LF1-2V	EME-G750SE
Wire	Cu Pd 0.7 mil	Cu Pd Au 0.7 mil
Package ball	Ball Diam 0.55mm / Alloy SACN38855	Ball Diam 0.55mm / Alloy SACN38855

TRACEABILITY

Dedicated Finished Good Codes

VALIDATION	According to ZVEI (AEC-Q100/Q006) recommendations, items: - SEM-PA-07 *(Die Attach material)* - SEM-PA-08 *(Change of wire bonding)* - SEM-PA-11 *(Change of mold compound / encapsulation material)* - SEM-PA-18 *(Move all or part of production to a different assembly site)*
CURRENT PRODUCTS	Current products assembly and testing will be transferred to ASE. ST assembly plants will remain active as alternative solution.
REPORTS	Transfer validation is presently in progress. Transfer validation report will be available within Q4 – 2023
IMPLEMENT.	The Start of Production is foreseen for Q4 - 2023

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SPC58NH9xC3x (FC92): BGA 17x17 Activation of ASE as Additional Assembly Plant
PCN Reference : ADG/23/14143

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC58NH92C3RMI0X		

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